

# Evaluation of damage formation and recovery in ion-implanted $\beta\text{-Ga}_2\text{O}_3$ by low-energy cathodoluminescence

Ion implantation and annealing are important processes in device manufacturing. Low-energy cathodoluminescence (CL) is highly sensitive to the damage caused by ion implantation and suitable for process optimization and failure analysis in  $\beta\text{-Ga}_2\text{O}_3$  based devices.

## Low-energy cathodoluminescence (CL)

### [Advantages]

#### 1. Surface analysis

Low-energy measurement enables surface analysis at nm level.

#### 2. Ultra-wide bandgap materials

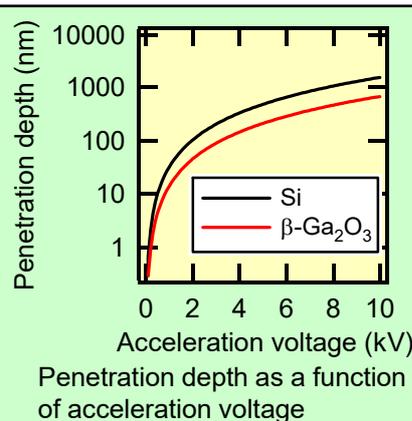
CL can be used for ultra-wide bandgap materials for which photoluminescence (PL) cannot be applicable.

#### 3. Device analysis

AlGaIn deep-UV LEDs, GaN HEMTs, SiC MOSFETs,  $\beta\text{-Ga}_2\text{O}_3$  transistors etc.

### [Application fields]

1. Process damage such as ion-implantation, dry etching etc.
2. Quality evaluation of thin gate oxide layers
3. Device failure analysis



Penetration depth in  $\beta\text{-Ga}_2\text{O}_3$   
 10.0 kV  $\rightarrow$   $L = 656$  nm  
 5.0 kV  $\rightarrow$   $L = 206$  nm  
 1.0 kV  $\rightarrow$   $L = 14$  nm  
 0.5 kV  $\rightarrow$   $L = 4.4$  nm

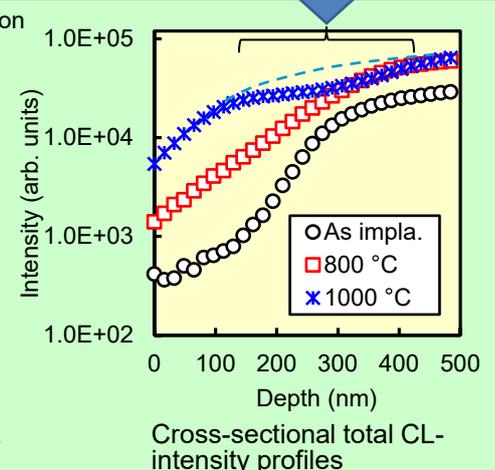
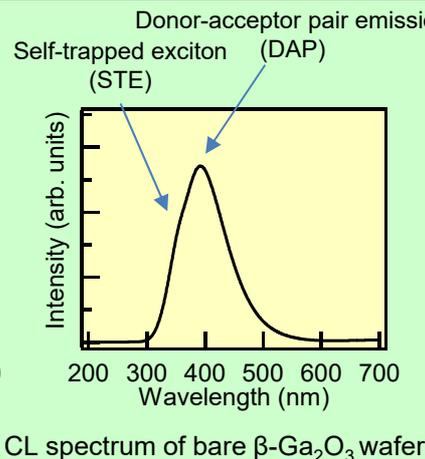
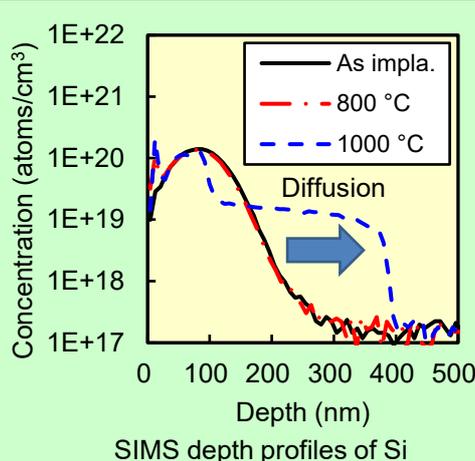
## Damage evaluation in ion-implanted $\beta\text{-Ga}_2\text{O}_3$ by low-energy CL<sup>1)</sup>

We implanted Si on  $\beta\text{-Ga}_2\text{O}_3$  bare wafers and annealed them at various temperatures. Ion-implantation damage and recovery were evaluated by low-energy cross-sectional CL.

### [Sample condition]

Wafer: Unintentionally-doped (-201) wafer  
 Dopant: Si, Energy: 100 keV  
 Dose:  $1\text{E}15$  atoms/cm<sup>2</sup>  
 Annealing temperature: 800, 1000 °C

Insufficient recovery around diffusion region



- Si diffusion was observed after annealing at 1000 °C.
- Total CL intensity increased after annealing. The intensities after annealing at 1000 °C are stronger than those after annealing at 800 °C. However, the CL-intensity profile after annealing at 1000 °C showed insufficient recovery around Si diffusion region. It suggests that the Si diffusion and damage recovery have strong correlation.

1) Appl. Phys. Exp. 13, 126502 (2020).